

Creative Materials, Inc.
12 Willow Road
Ayer, MA 01432

T 978.391.4700
F 978.391.4705

118-23

B-STAGED, ELECTRICALLY CONDUCTIVE, TRANSFERABLE, EPOXY ADHESIVE FILM 3.0 MILS

DESCRIPTION: 118-23 is a B-staged, electrically conductive, transferable, epoxy adhesive film. Some applications for 118-23 include, but are not limited to, conductive splicing of ribbon cables, PTF circuits, and electrical attachment of SMD devices, as well as the assembling electrical and electronic components. This system features excellent thermal stability and high temperature properties. This product has been formulated to have improved handleability in the B-staged form.

PHYSICAL DATA:

Substrate Type	Release Liner
Conductive Coating Type	Silver/polymer
Conductive Coating Thickness (mils)	3.0
Volume Resistivity (Ω -cm)	0.001
Solderable	No
Useful Temperature Range ($^{\circ}$ C)	-55 to 200
Lap Shear Strength, min. (psi)	1500

STORAGE: Shelf Life: 12 months at -40° C (*).

* Avoid flexing film if stored at -40° C.

PROCEDURE FOR APPLYING 118-23

1. As with all adhesive bonds, surface preparation is a vital part of the process. Carefully clean both surfaces to be bonded with MEK if possible. If MEK is not compatible with the surfaces to be bonded, another suitable solvent may be used.
2. Allow cleaned surfaces to dry completely.
3. Die cut 118-23 to the of the size of interface area, remove one of the protective liners, position onto one of the surfaces to be bonded, and warm the substrate/adhesive to 50° C- 70° C.
4. By applying slight pressure, laminate the film/adhesive to the substrate smoothing out any trapped air. Allow to cool to room temperature and peel off the other release liner.
5. Position the other substrate and apply a clamp to provide constant pressure.
6. Cure for 1 hour at 150° C.
7. Remove pressure. Part is ready for use.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

REVISION DATE: 2/14/97 REVISION: A